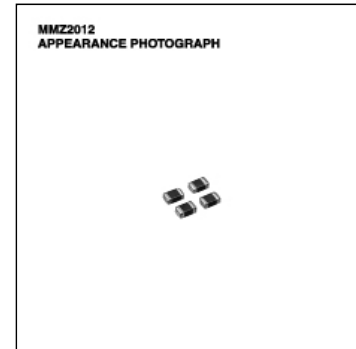




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Product Name **Chip Beads**
Series **MMZ Series**
Type **2012 Type**
Part Number **MMZ2012R121AT000**

Product Lifecycle Stage PROD



Specification

Mounting Method Flag	Yes	
Processing	MULTI-LAYER	
Shape	Chip	
Number of Circuits	Nom	1
Material Code	R	
Size Code	2012	
Body Length(L)	Nom	2 m m
Body Breadth(W)	Nom	1.25 m m
Body Height(T)	Nom	0.85 m m
Impedance	Min	90 Ohm
Impedance	Nom	120 Ohm
Impedance	Min	-25 %
Impedance Tolerance	Max	25 %
Frequency of Impedance	Nom	100 M Hz
Rated Current	Max	0.8 A
DC Resistance	Max	0.12 Ohm
Soldering Method	Flow,Reflow,Iron Soldering	
Category Temperature	Min	-55 Cel
Range	Max	125 Cel
Storage Temperature Range	Min	-55 Cel
	Max	125 Cel
Weight	Nom	0.008 g

⚠ [Caution]

Specifications which provide more details for the proper and safe use of the described product are available upon request.

⚠ [Notice of Revision and Improve]

All specifications are subject to change without notice.

Summary/Applications/Feature

Summary The MMZ series provide effective EMC suppression in signal lines through simple in-series implementation. It is applicable for lead free soldering.

Applications General EMI suppression.
 (RADIATION,IMMUNITY) For PC,CD-ROM,DVD and DVD-ROM,TV,VIDEO CAMERA,PDP,LCD-PANEL,MOBIL COMMUNICATIONS etc.

Feature The MMZ series provide effective EMC suppression in signal lines through simple in-series implementation.
 It is applicable for lead free soldering.

Packaging

Packing	Punched (Paper)Taping [180mm Reel]	
Minimum Package Qty	Nom	4000 Pcs
Minimum Order Qty	Nom	4000 Pcs

[Details](#)

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